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For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects

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APPLICATION DATA SHEET

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(3) APPLICANT INFORMATION

Title Method and Apparatus for Evaluating a
Known Good Die Using Both Wire Bond and
Flip-Chip Interconnects
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Type of Application Utility

This case is a Divisional of USPTO Serial
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(4) REPRESENTATIVE INFORMATION

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(5) DOMESTIC PRIORITY INFORMATION

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Number 09/321,565, filed May 28, 1999 and
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(6) FOREIGN PRIORITY INFORMATION

None

(7) ASSIGNEE INFORMATION

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